

# 2A, 200V - 1000V High Efficient Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

## **MECHANICAL DATA**

• Case: SOD-123FL

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

Meet JESD 201 class 1 whisker test

Polarity: Indicated by cathode band

• Weight: 0.016g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	2	Α	
$V_{RRM}$	200 - 1000	V	
I <sub>FSM</sub>	40	Α	
$T_{JMAX}$	150	°C	
Package	SOD-123FL		
Configuration	Single die		









SOD-123FL



PARAMETER		SYMBOL	HS2DFL	HS2GFL	HS2JFL	HS2KFL	HS2MFL	UNIT
Marking code on the device			H2DF	H2GF	H2JF	H2KF	H2MF	
Repetitive peak reverse voltage		$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I <sub>F</sub>	2					Α
Surge peak forward current, single half sine $t = 8$ .		I		40				Α
-wave superimposed on rated load	t = 1.0ms	I <sub>FSM</sub>	100					Α
Junction temperature		TJ	-55 to +150			°C		
Storage temperature		T <sub>STG</sub>	T <sub>STG</sub> -55 to +150			°C		

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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R <sub>eJL</sub>	81	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	116	°C/W	
Junction-to-case thermal resistance	R <sub>eJC</sub>	69	°C/W	

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		$I_F = 1A, T_J = 25^{\circ}C$		0.84	-	V
	HOODEL	I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C		0.93	1.00	V
	HS2DFL	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		0.73	-	V
		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		0.83	0.95	V
		I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C		0.94	-	V
Forward voltage <sup>(1)</sup>	HS2GFL	I <sub>F</sub> = 2A, T <sub>J</sub> = 25°C	V	1.06	1.30	V
Forward voitage	H52GFL	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.80	-	V
		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		0.93	1.09	V
		I <sub>F</sub> = 1A, T <sub>J</sub> = 25°C		1.24	-	V
	HS2JFL	$I_F = 2A, T_J = 25^{\circ}C$		1.42	1.70	V
	HS2KFL HS2MFL	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C		1.04	-	V
		I <sub>F</sub> = 2A, T <sub>J</sub> = 125°C		1.24	1.50	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 25°C	,	-	5	μΑ
		T <sub>J</sub> = 125°C	$ I_R$	-	125	μΑ
HS2DI HS2GI		I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A,		-	50	ns
Reverse recovery time	HS2JFL HS2KFL HS2MFL	$I_{rr} = 0.25A$	t <sub>rr</sub>	-	75	ns
Junction capacitance	HS2DFL		CJ	21	-	pF
	HS2GFL	1MHz, V <sub>R</sub> = 4.0V		16	-	pF
	HS2JFL HS2KFL HS2MFL	11VII12, V <sub>R</sub> = 4.0V		10	-	pF

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
HS2xFL	SOD-123FL	10,000 / Tape & Reel	

#### Notes

1. "x" defines voltage from 200V(HS2DFL) to 1000V(HS2MFL)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

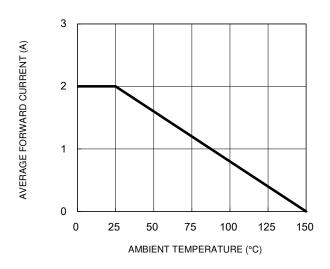


Fig.3 Typical Reverse Characteristics

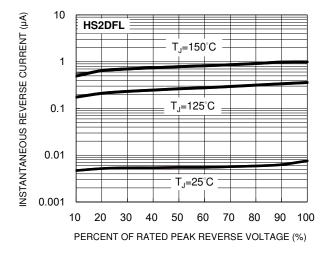
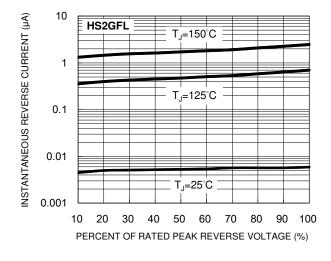
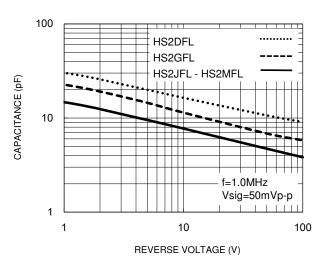


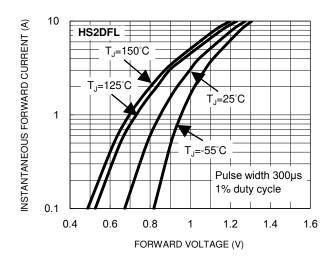
Fig.5 Typical Reverse Characteristics



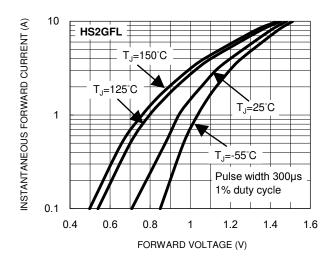
**Fig.2 Typical Junction Capacitance** 



**Fig.4 Typical Forward Characteristics** 



**Fig.6 Typical Forward Characteristics** 

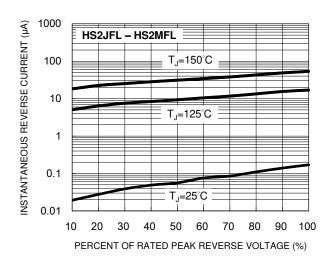




## **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.7 Typical Reverse Characteristics



**Fig.8 Typical Forward Characteristics** 

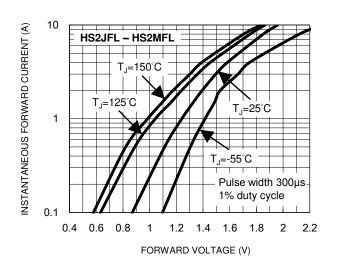
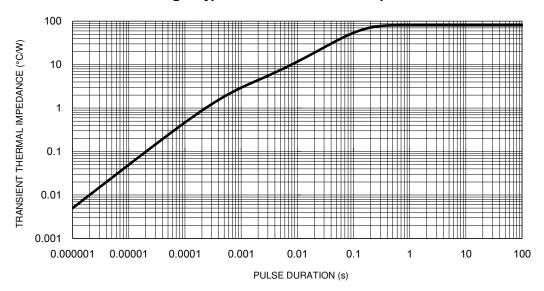


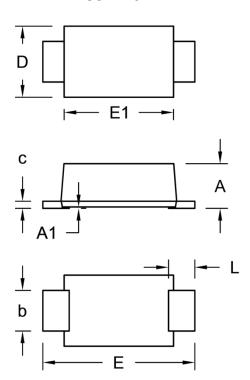
Fig.9 Typical Transient Thermal Impedance





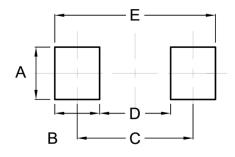
# **PACKAGE OUTLINE DIMENSIONS**

SOD-123FL



DIM.	Unit (mm)		Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
Α	1.00	1.20	0.039	0.047
A1	0.02	0.05	0.001	0.002
b	0.90	1.10	0.035	0.043
С	0.10	0.25	0.004	0.010
D	1.60	1.90	0.063	0.075
E	3.60	3.90	0.142	0.154
E1	2.55	2.85	0.100	0.112
Ĺ	0.40	0.90	0.016	0.035

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

## **MARKING DIAGRAM**



P/N = Marking Code = Date Code ΥW F = Factory Code



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